ON Semiconductor®



Title of Change:	Samsung Chemical Sol	Samsung Chemical Solder Pin Qualification for Power Integrated Module (PIM) products.			
Proposed First Ship date:	19 May 2020 or earlie	19 May 2020 or earlier if approved by customer.			
Contact Information:	Contact your local ON	Contact your local ON Semiconductor Sales Office or < <u>Way-Shan.Yong@onsemi.com</u> >			
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCI Samples delivery timir	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>			
Additional Reliability Data:	Contact your local ON	Contact your local ON Semiconductor Sales Office or < <u>Phine.Guevarra@onsemi.com</u> >			
Type of Notification:	days prior to impleme ON Semiconductor wil	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com			
Marking of Parts/ Traceability of Change:	No change in marking	No change in marking			
Change Category:	Assembly Change	Assembly Change			
Change Sub-Category(s):	Material Change	Material Change			
Sites Affected:	·				
ON Semiconductor Sites		External Foundry/Subcon Sites			
ON Semiconductor Shenzhen, China		one			
Description and Purpose:					
This FPCN announces the qualification of S	amsung solder pins for GEN	IIII product as alternate to Interplex solder pins.			

The change is planned at ON Semiconductor Shenzhen, China.

Upon the expiration of this PCN, PIM modules production at ON Semiconductor Shenzhen will use either Interplex or Samsung pins for GENIII module production.

Products has been qualified to industrial requirements and meeting customer pin press-in requirements.

	Before Change Description	After Change Description	
Module Lead Attach Pins	Interplex pins only	Interplex and Samsung pins	

There is no product marking change as a result of this change.

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-	eliability Data Summary: QV DEVICE NAME : NXH160T120L2Q2F2SG								
RMS Package	: K58642 : Q2Pack								
Test	Specification	с	ondition	Interval	Result				
TC	JESD22-A104	- 40°C to 125°C, Temperature soak = 30 min, Transition time = 20 min max		100 сус	0/11				
VVF	JESD22-B103	Perform 25-500Hz/15min 10G, with 2hrs for X-axis, 2hrs for Y- axis, 2hrs for Z-axis		6hrs	0/11				
	ractoristics Summary								
Electrical Characteristics Summary:									
ist of Affecte	ist of Affected Parts:								
Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the custome specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u> .									
Part Number			Qualification Vehicle						
NXH450N65L4Q2F2SG			NXH160T120L2Q2F2SG						